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(IEC 62680-1-3:2016)

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universel en série - Composants communs - Spécification
des câbles et connecteurs de type C™ de bus universel en
série
(IEC 62680-1-3:2016)

Universelle serielle Bus Schnittstellen für Daten und
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Gemeinsame Komponenten - USB-Typ-C™ Kabel und
Steckverbinder Spezifikation
(IEC 62680-1-3:2016)

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INTERNATIONAL STANDARD



**Universal serial bus interfaces for data and power –
Part 1-3: Universal Serial Bus interfaces – Common components –
USB Type-C™ cable and connector specification**





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**Universal serial bus interfaces for data and power –
Part 1-3: Universal Serial Bus interfaces – Common components –
USB Type-C™ cable and connector specification**

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The text of this standard was prepared by the USB Implementers Forum (USB-IF). The structure and editorial rules used in this publication reflect the practice of the organization which submitted it.

The text of this standard is based on the following documents:

CDV	Report on voting
100/2587/CDV	100/2681/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

A list of all parts in the IEC 62680 series, published under the general title *Universal serial bus interfaces for data and power*, can be found on the IEC website.

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This standard is the USB-IF publication USB Type-C™ Cable and Connector Specification Revision 1.1.

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Universal Serial Bus Type-C Cable and Connector Specification

**Revision 1.1
April 3, 2015**

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Revision History

Revision	Date	Description
1.0	August 11, 2014	Initial Release
1.1	April 3, 2015	Reprint release including incorporation of all approved ECNs as of the revision date plus editorial clean-up.

1 Introduction

With the continued success of the USB interface, there exists a need to adapt USB technology to serve newer computing platforms and devices as they trend toward smaller, thinner and lighter form-factors. Many of these newer platforms and devices are reaching a point where existing USB receptacles and plugs are inhibiting innovation, especially given the relatively large size and internal volume constraints of the Standard-A and Standard-B versions of USB connectors. Additionally, as platform usage models have evolved, usability and robustness requirements have advanced and the existing set of USB connectors were not originally designed for some of these newer requirements. This specification is to establish a new USB connector ecosystem that addresses the evolving needs of platforms and devices while retaining all of the functional benefits of USB that form the basis for this most popular of computing device interconnects.

1.1 Purpose

This specification defines the USB Type-C™ receptacles, plug and cables.

The USB Type-C Cable and Connector Specification is guided by the following principles:

- Enable new and exciting host and device form-factors where size, industrial design and style are important parameters
- Work seamlessly with existing USB host and device silicon solutions
- Enhance ease of use for connecting USB devices with a focus on minimizing user confusion for plug and cable orientation

The USB Type-C Cable and Connector Specification defines a new receptacle, plug, cable and detection mechanisms that are compatible with existing USB interface electrical and functional specifications. This specification covers the following aspects that are needed to produce and use this new USB cable/connector solution in newer platforms and devices, and that interoperate with existing platforms and devices:

- USB Type-C receptacles, including electro-mechanical definition and performance requirements
- USB Type-C plugs and cable assemblies, including electro-mechanical definition and performance requirements
- USB Type-C to legacy cable assemblies and adapters
- USB Type-C-based device detection and interface configuration, including support for legacy connections
- USB Power Delivery optimized for the USB Type-C connector

The USB Type-C Cable and Connector Specification defines a standardized mechanism that supports Alternate Modes, such as repurposing the connector for docking-specific applications.

1.2 Scope

This specification is intended as a supplement to the existing [USB 2.0](#), [USB 3.1](#) and [USB Power Delivery](#) specifications. It addresses only the elements required to implement and support the USB Type-C receptacles, plugs and cables.

Normative information is provided to allow interoperability of components designed to this specification. Informative information, when provided, may illustrate possible design implementations.

1.3 Related Documents

- USB 2.0** *Universal Serial Bus Revision 2.0 Specification*
This includes the entire document release package.
<http://www.usb.org/developers/docs>
- USB 3.1** *Universal Serial Bus Revision 3.1 Specification*
This includes the entire document release package.
<http://www.usb.org/developers/docs>
- USB PD** *USB Power Delivery Specification, Revision 2.0, August 11, 2014*
<http://www.usb.org/developers/docs>
- USB BB** *USB Billboard Device Class Specification, Revision 1.0, August 11, 2014*
<http://www.usb.org/developers/docs>
- USB BC** *Battery Charging Specification, Revision 1.2 (including errata and ECNs through March 15, 2012), March 15, 2012*
<http://www.usb.org/developers/docs>

1.4 Conventions

1.4.1 Precedence

If there is a conflict between text, figures, and tables, the precedence shall be tables, figures, and then text.

1.4.2 Keywords

The following keywords differentiate between the levels of requirements and options.

1.4.2.1 Informative

Informative is a keyword that describes information with this specification that intends to discuss and clarify requirements and features as opposed to mandating them.

1.4.2.2 May

May is a keyword that indicates a choice with no implied preference.

1.4.2.3 N/A

N/A is a keyword that indicates that a field or value is not applicable and has no defined value and shall not be checked or used by the recipient.

1.4.2.4 Normative

Normative is a keyword that describes features that are mandated by this specification.

1.4.2.5 Optional

Optional is a keyword that describes features not mandated by this specification. However, if an optional feature is implemented, the feature shall be implemented as defined by this specification (optional normative).

1.4.2.6 Reserved

Reserved is a keyword indicating reserved bits, bytes, words, fields, and code values that are set-aside for future standardization. Their use and interpretation may be specified by future extensions to this specification and, unless otherwise stated, shall not be utilized or adapted by vendor implementation. A reserved bit, byte, word, or field shall be set to zero by the sender and shall be ignored by the receiver. Reserved field values shall not be sent by the sender and, if received, shall be ignored by the receiver.

1.4.2.7 Shall

Shall is a keyword indicating a mandatory (normative) requirement. Designers are mandated to implement all such requirements to ensure interoperability with other compliant Devices.

1.4.2.8 Should

Should is a keyword indicating flexibility of choice with a preferred alternative. Equivalent to the phrase “it is recommended that”.

1.4.3 Numbering

Numbers that are immediately followed by a lowercase “b” (e.g., 01b) are binary values. Numbers that are immediately followed by an uppercase “B” are byte values. Numbers that are immediately followed by a lowercase “h” (e.g., 3Ah) are hexadecimal values. Numbers not immediately followed by either a “b”, “B”, or “h” are decimal values.

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